

October 2007

### HUF75344A3

# N-Channel UltraFET Power MOSFET 55V, 75A, $8m\Omega$

#### **Features**

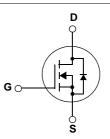
- $R_{DS(on)} = 6.5 \text{m}\Omega \text{ (Typ.)} @ V_{GS} = 10 \text{V, } I_D = 75 \text{A}$
- · RoHS compliant



### **Description**

• This N-channel power MOSFET is produced using Fairchild Semiconductor's innovative UltraFET process. This advanced process technology achieves the lowest possible on-resistance per silicon area, resulting in outstanding performance. This device is capable of withstanding high energy in the avalanche mode and the diode exhibits very low reverse recovery time and stored change. It was designed for use in applications where power efficiency is important, such as switching regulators, switching converters, motro drives, relay drivers, low-voltage bus switches, and power management in portable and battery-operated products.





### **MOSFET Maximum Ratings** $T_C = 25^{\circ}C$ unless otherwise noted

Symbol		Parameter		Ratings	Units
V <sub>DSS</sub>	Drain to Source Voltage	rain to Source Voltage			V
V <sub>GSS</sub>	Gate to Source Voltage	Sate to Source Voltage			V
I <sub>D</sub>	Drain Current	-Continuous (T <sub>C</sub> = 130°C)		75	Α
I <sub>DM</sub>	Drain Current	- Pulsed		300	Α
E <sub>AS</sub>	Single Pulsed Avalanche Er	Single Pulsed Avalanche Energy (Note 1)		1153	mJ
Б	Pawer Dissipation	$(T_C = 25^{\circ}C)$		288.5	W
$P_{D}$	Power Dissipation	- Derate above 25°C		1.92	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Tem	perature Range		-55 to +175	°C
TL	Maximum Lead Temperatur 1/8" from Case for 5 Second			300	°C

### **Thermal Characteristics**

Symbol	Parameter	Ratings	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.52	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	40	C/VV

### Package Marking and Ordering Information $T_C = 25^{\circ}C$ unless otherwise noted

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
HUF75344A3	HUF75344A3	TO-3PN	=	-	30

### **Electrical Characteristics**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250\mu A$ , $V_{GS} = 0V$ , $T_J = 25^{\circ}C$	55	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, Referenced to 25°C	-	0.07	-	V/°C
_	Inss Zero Gate Voltage Drain Current	$V_{DS} = 50V, V_{GS} = 0V$	-	-	1	
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 45V, V_{GS} = 0V, T_{J} = 150^{\circ}C$	-	-	250	μΑ
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA

### On Characteristics

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 250\mu A$	2	-	4	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10V, I_D = 75A$		6.5	8.0	mΩ

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 05V V 0V	$V_{DS} = 25V, V_{GS} = 0V$		3650	4855	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V$ f = 1MHz			980	1305	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1101112		-	135	205	pF
$Q_{g(tot)}$	Total Gate Charge at 20V	$V_{GS} = 0V \text{ to } 20V$		-	160	208	nC
Q <sub>g(10)</sub>	Total Gate Charge at 10V	$V_{GS} = 0V \text{ to } 10V$	$V_{DS} = 30V$	-	86	112	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0V \text{ to } 2V$	$I_{D} = 75A$		7	9	nC
$Q_{gs}$	Gate to Source Gate Charge		$I_g = 1mA$	-	17	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge			-	28	-	nC

### **Switching Characteristics**

$t_{ON}$	Turn-On Time		-	146	310	ns
t <sub>d(on)</sub>	Turn-On Delay Time		-	19	48	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 30V, I_{D} = 75A$ $V_{GS} = 10V, R_{GEN} = 3\Omega$	-	126	262	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> = 10V, R <sub>GEN</sub> = 352	-	61	130	ns
t <sub>f</sub>	Turn-Off Fall Time		-	20	48	ns
t <sub>OFF</sub>	Turn-Off Time		-	80	178	ns

### **Drain-Source Diode Characteristics**

$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 75A	-	-	1.25	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0V, I_{SD} = 75A$	-	79	-	ns
$Q_{rr}$	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	-	270	-	nC

Notes: 1: L = 0.41mH,  $I_{AS}$  = 75A,  $V_{DD}$  = 50V,  $V_{GS}$  = 10V,  $R_{G}$  = 25Ω, Starting  $T_{J}$  = 25°C

### **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

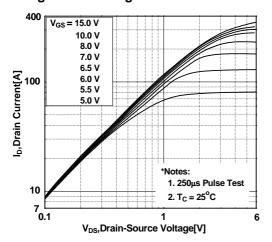


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

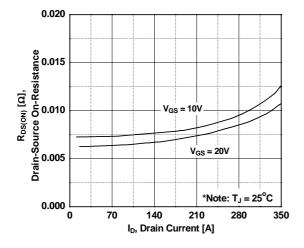


Figure 5. Capacitance Characteristics

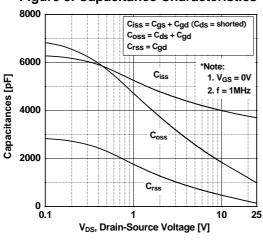


Figure 2. Transfer Characteristics

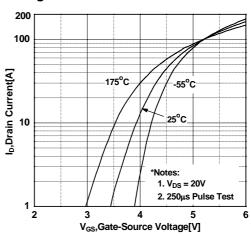


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

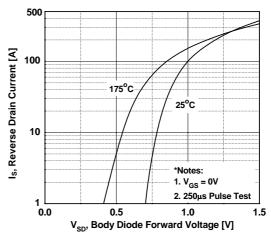
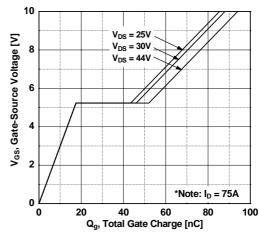


Figure 6. Gate Charge Characteristics



### Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

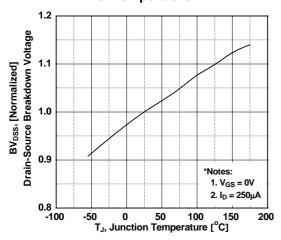


Figure 8. On-Resistance Variation vs. Temperature

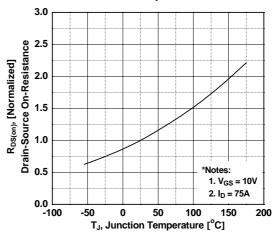


Figure 9. Maximum Safe Operating Area

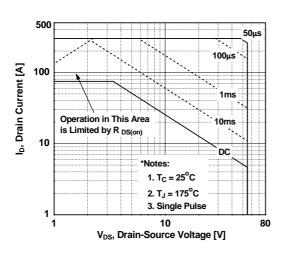


Figure 10. Maximum Drain Current vs. Case Temperature

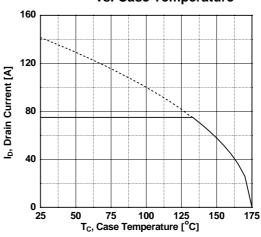
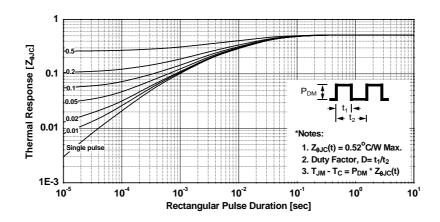
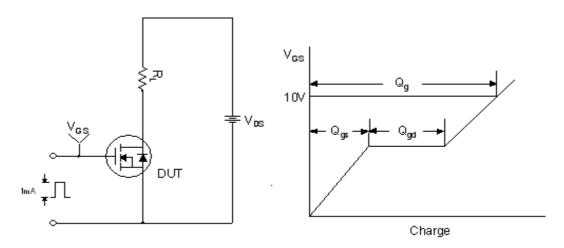


Figure 11. Transient Thermal Response Curve

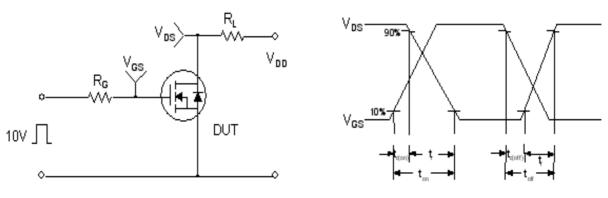


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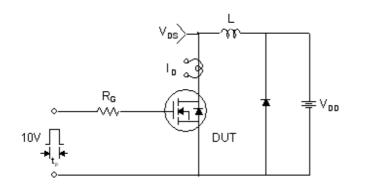
### **Gate Charge Test Circuit & Waveform**

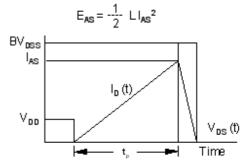


### **Resistive Switching Test Circuit & Waveforms**

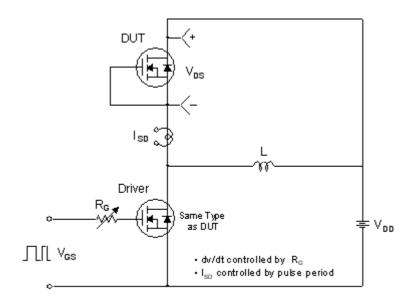


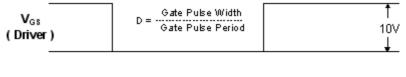
**Unclamped Inductive Switching Test Circuit & Waveforms** 

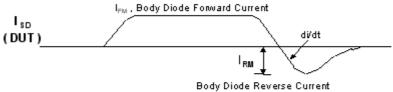


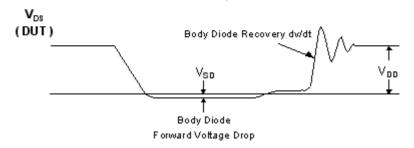


### Peak Diode Recovery dv/dt Test Circuit & Waveforms



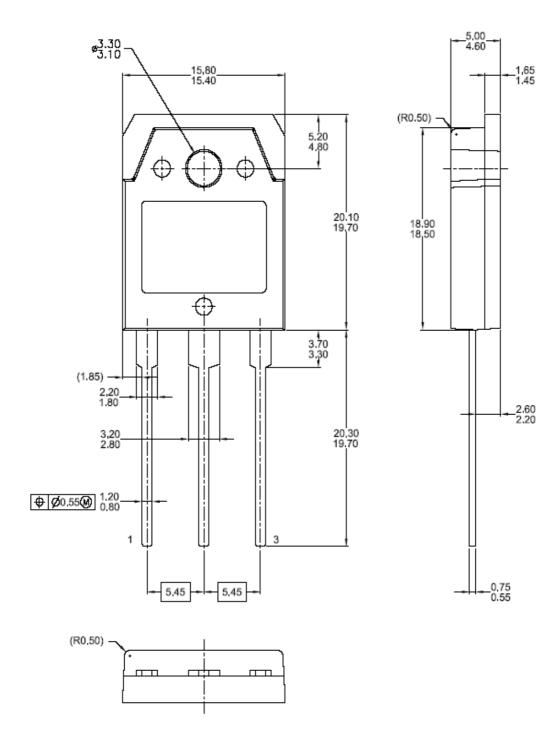






### **Mechanical Dimensions**

## TO-3PN



Dimensions in Millimeters





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